

1 Customer drawings

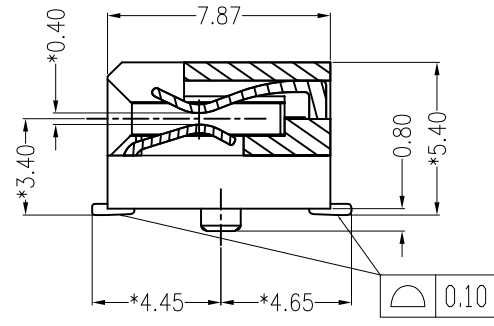
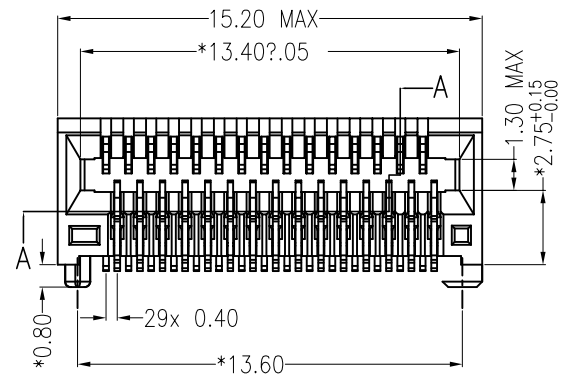
NOTE:  
 MATERIAL:  
 1. TERMINAL: COPPER ALLOY  
 2. HOUSING: HIGH TEMPERATURE THERMOPLASTIC  
 GLASS FILLED UL 94V-0. COLOR: BLACK

PLATED:  
 OPTION1:  
 1.1. CONTACT AREA : PLATING GOLD 0.38 MICROMETERS MINIMUM  
 OVER 1.25~2.54 MICROMETERS NICKEL.  
 1.2. SURFACE MOUNT CONTACT: 1.25~2.54 MICROMETERS MATTE TIN  
 OVER 1.25~2.54 MICROMETERS NICKEL.

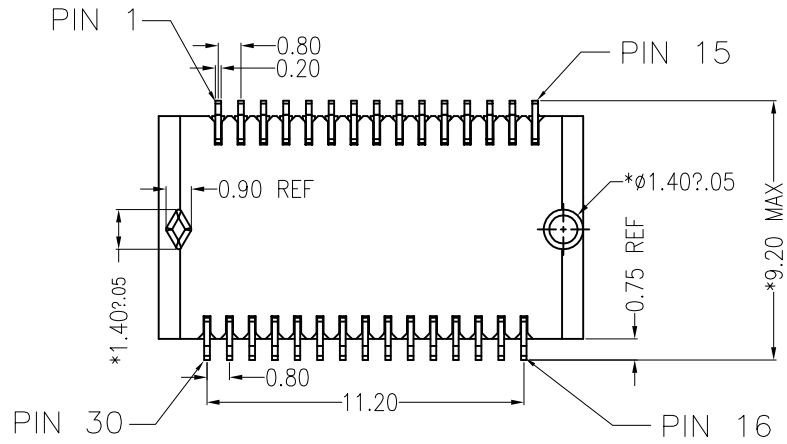
OPTION2:  
 2.1. CONTACT AREA : PLATING GOLD 0.76 MICROMETERS MINIMUM  
 OVER 1.25~2.54 MICROMETERS NICKEL.  
 2.2. SURFACE MOUNT CONTACT: 1.25~2.54 MICROMETERS MATTE TIN  
 OVER 1.25~2.54 MICROMETERS NICKEL.

ELECTRICAL:  
 1. CONTACT CURRENT RATING:0.5 Amps MAX.  
 2. VOLTAGE RATING:30 Volts AC (RMS)/DC MAX.  
 3. CONTACT RESISTANCE: ΔR 10 MILLIOHMS MAXIMUM FOR SIGNAL CONTACTS.  
 4. DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/MIN.

ENVIRONMENT:  
 1. OPERATION: -40°C~+85°C.  
 2. STORAGE: -55°C~+105°C.  
 3. REFLOW SOLDERING TEMPERATURE:260° MAXIMUM FOR 30 SECONDS.  
 4. ROHS COMPLIANT



SECTION A-A



ROHS PART NUMBER	DESCRIPTION	CONTACT PLATING GOLD
81-141-40001-1	CONNECTOR, XFP 1*1 SMT Type	0.38 MICROMETERS
81-141-50001-1	CONNECTOR, XFP 1*1 SMT Type	0.76 MICROMETERS

自由公差			
长度尺寸	角度尺寸		
X. ±0.35	X° ±0.5°		
.XX ±0.35	.X° ±0.5°		
.XX ±0.25	.XX° ±0.5°		
.XXX ±0.15			
单位 mm	比例 1:1		
A4	页次 1 of 2		

版次	修改说明	ECN 编号	核准

设计

审核

核准

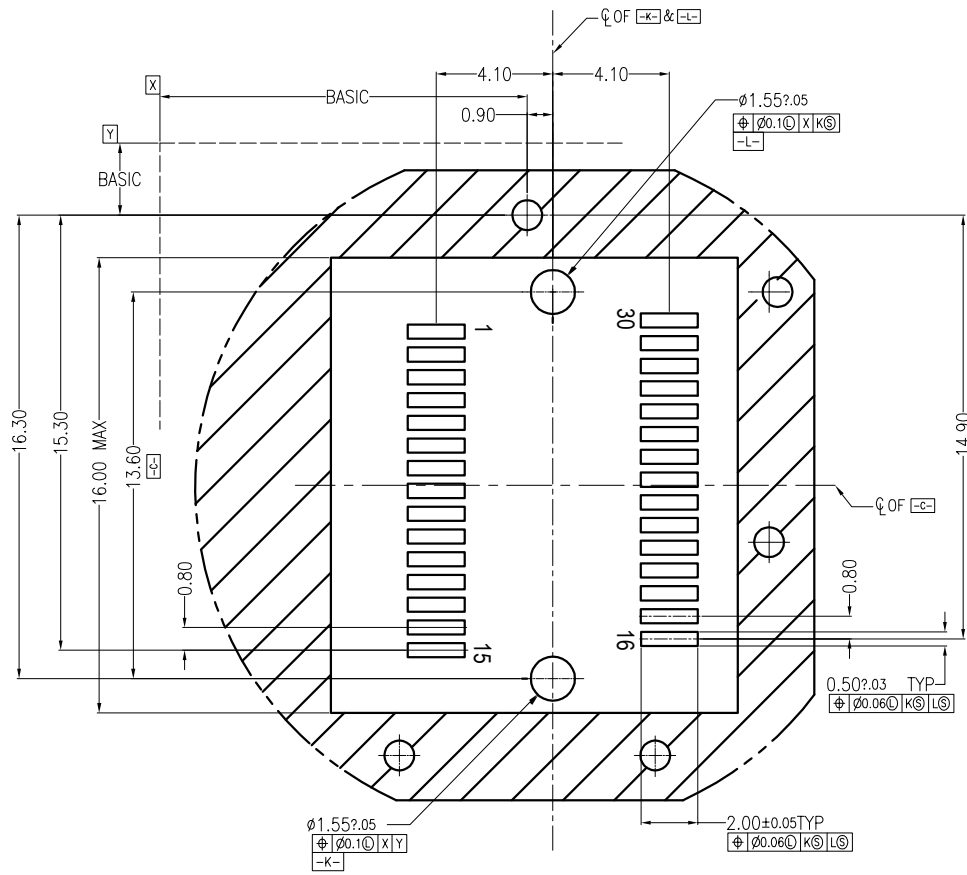
深圳市益晟康科技有限公司  
 ETLINK SHENZHEN ETLINK TECHNOLOGY CO.,LTD

品名 XFP 1x1 CONNECTOR

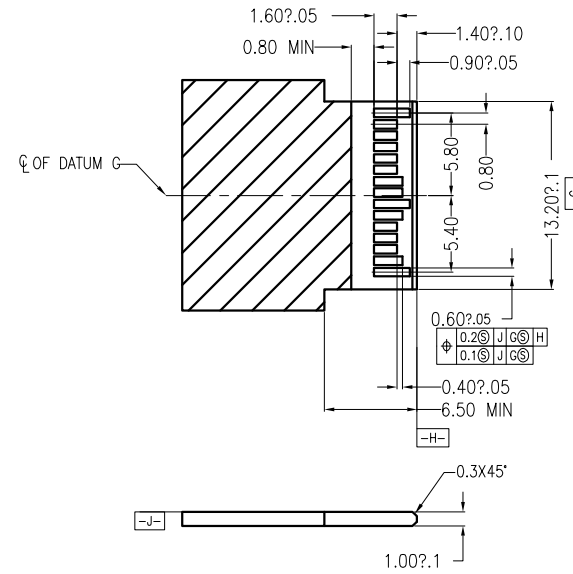
料号 SEE TABLE

图号 ESFP15032704-C 版本: A

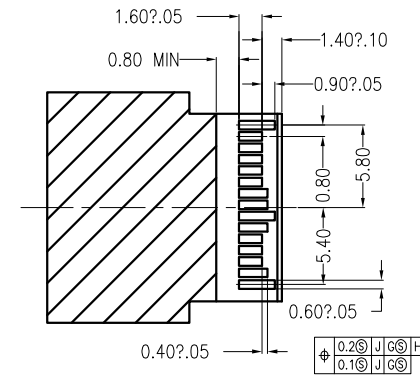
Customer drawings



RECOMMENDED PCB LAYOUT CONNECTOR  
MOUNTING SIDE  
2:1



RECOMMENDED PATTERN LAYOUT FOR XFP  
PRINTED CIRCUIT



自由公差			
长度尺寸	角度尺寸	设计	
X. ±0.35	.X' ±0.5°	审核	
.XX ±0.25	.XX' ±0.5°		
.XXX ±0.15	.XXX' ±0.5°		
单位	mm	比例	1:1
版次	修改说明	ECN 编号	核准
		A4	页次 2 of 2

**ETLINK** 深圳市益晟康科技有限公司  
ETLINK SHENZHEN ETLINK TECHNOLOGY CO.,LTD

品名	XFP 1x1 CONNECTOR
料号	SEE TABLE
图号	ESFP15032704-C
版本	A